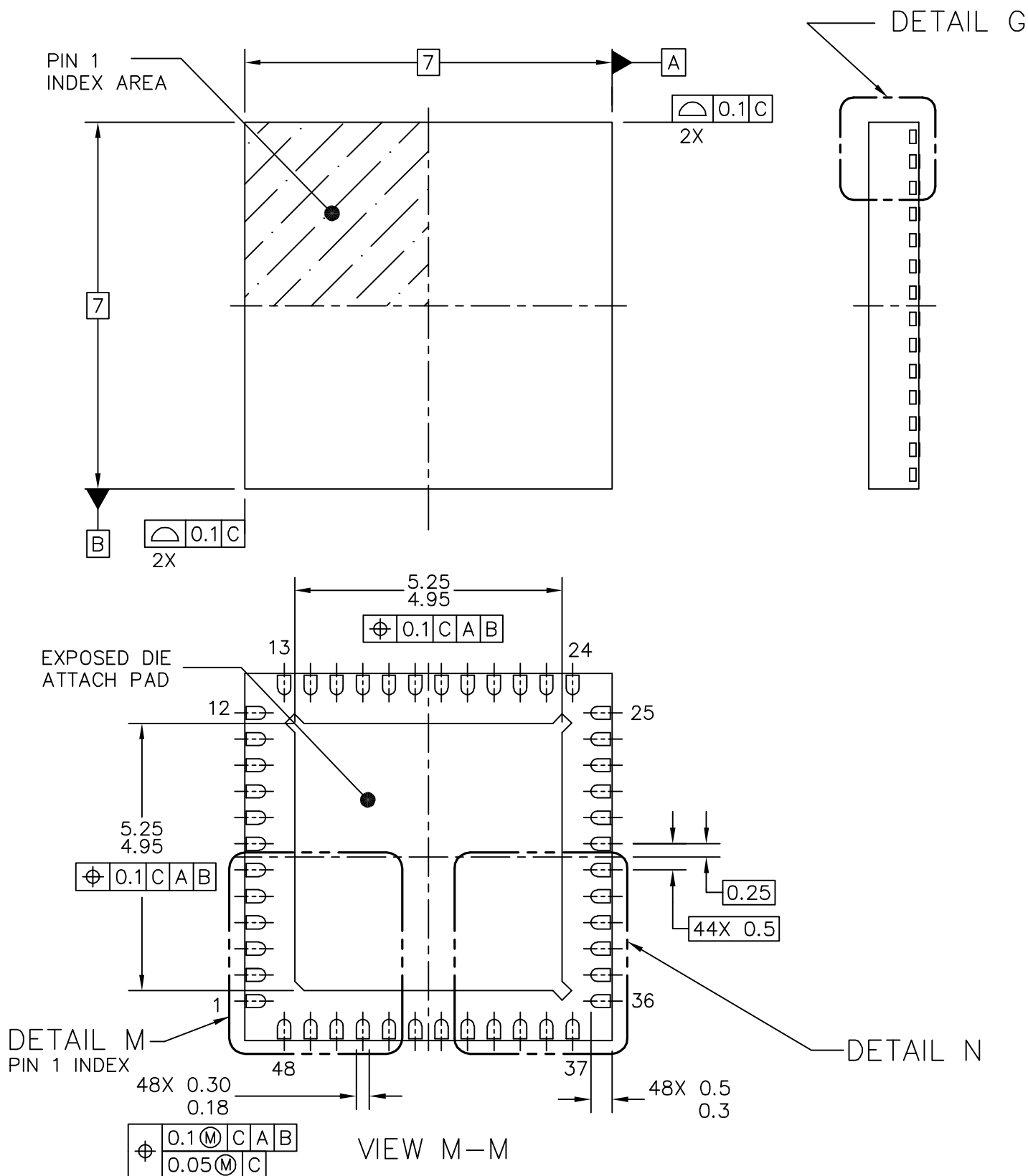
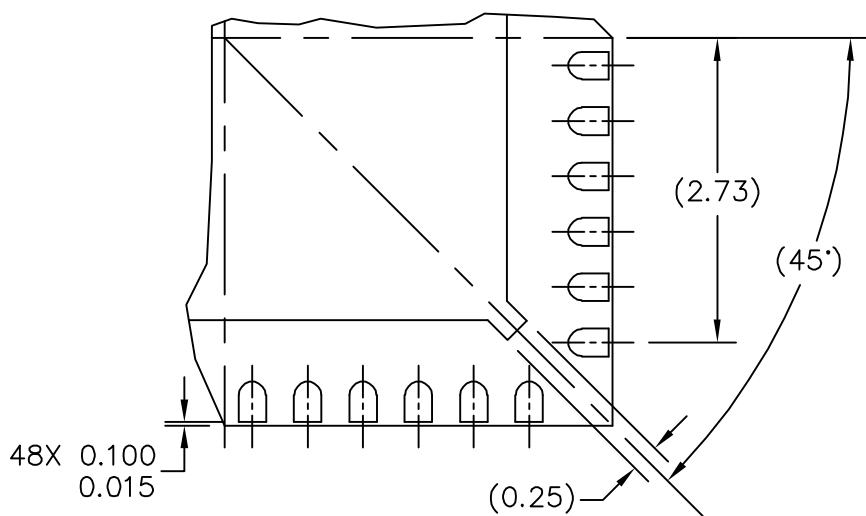
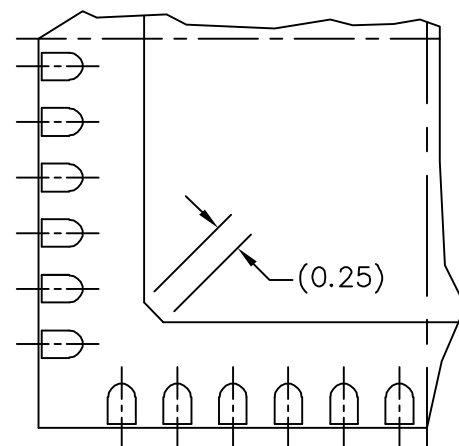




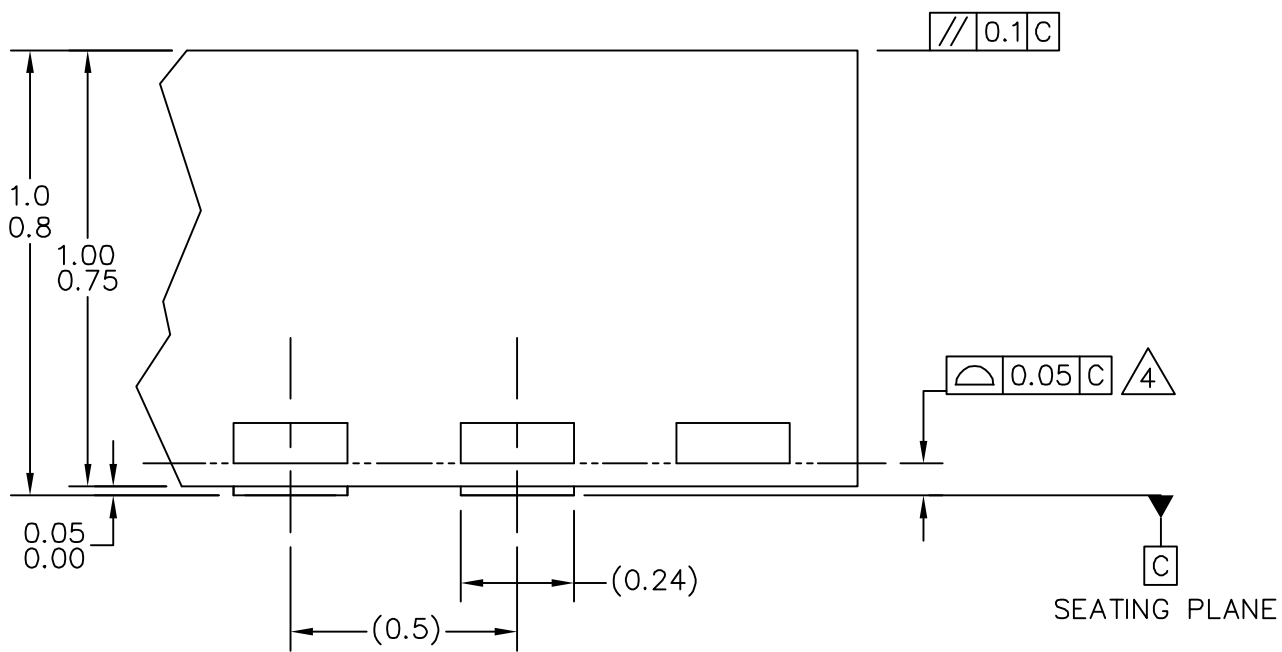
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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 1, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ARH99048A REV: H	
	STANDARD: JEDEC-MO-220 VKKD-2	
	08 JUL 2015	



DETAIL N
PREFERRED CORNER CONFIGURATION



DETAIL M
PREFERRED PIN 1 BACKSIDE IDENTIFIER



DETAIL G
VIEW ROTATED 90° CW

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		STANDARD: JEDEC-MO-220 VKKD-2	
		08 JUL 2015	

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
-  4. COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2MM.

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